



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Seong Min Seo, Young Suk Chung, Jong Sik Paek, Jae Hun Ku, Jae Hak Yee

Assignee: Amkor Technology, Inc.

Title: Semiconductor Package Including Stacked Chips

Serial No.: 09/816,599

Filing Date: March 23, 2001

Examiner: Not Yet Assigned

Group Art Unit: 2811

Docket No.: AB-1111 US

RECEIVED

AUG 20 2002

Technology Center 2600

San Jose, California

February 19, 2002

BOX DAC  
COMMISSIONER FOR PATENTS  
Washington, D. C. 20231

REQUEST FOR RECONSIDERATION OF PETITION UNDER 37 CFR 1.47(A)

Dear Sir:

A Decision Refusing Status Under 37 CFR 1.47(a) was mailed on December 26, 2001.

Subsequently, the inventors who previously did not sign an inventor Declaration, namely, Jae Hun Ku and Jae Hak Yee, have executed a Declaration for Patent Application. The executed Declaration is enclosed herewith. Accordingly, the Petition is moot. Please put copies of the executed Declaration for Patent Application in the file of the application, and please notify the undersigned that the matter is resolved.

EXPRESS MAIL LABEL NO:  
EL 937 082 926 US

Respectfully submitted,

James E. Parsons  
Attorney for Applicants  
Reg. No. 34,691

RECEIVED

FEB 22 2002

OFFICE OF PETITIONS

RECEIVED

SEP 05 2002

OFFICE OF PETITIONS

LAW OFFICES OF  
SKJERVEN MORRILL  
MACPHERSON LLP

25 METRO DRIVE  
SUITE 700  
SAN JOSE, CA 95110  
(408) 453-9200  
FAX (408) 453-7979